## Product Features

- +27.8 dBm Input IP3
- RF: 1 - 2700 MHz
- LO: 1 - 2700 MHz
- IF: $1-2000 \mathrm{MHz}$
- +17 dBm LO Drive Level
- No Internal Solder Connections
- Lead Free/RoHS-compliant SMT package
- No External Bias Required


## Product Description

The WJZ1020H is a passive double-balanced diode-ring mixer that provides high dynamic range performance in a Lead Free/ RoHS-compliant surface mount package. The mixer is nominally driven with a LO input power of +17 dBm to optimize its performance. Other WJZ models are available for other LO drive levels.

Targeted applications include frequency up/down conversion, modulation and demodulation for receivers and transmitters used in 2.5G and 3G GSM/CDMA/W-CDMA systems. The device can also be used in Radar, Satellite, Test / Medical Instruments, Avionics communications and Navigation markets.

## Functional Diagram



Top View

## Applications

- Up/down frequency conversion
- Phase Detector
- Image Rejection
- Current Controlled Attenuator


## Specifications



1. Measured in a 50 ohm system with a nominal LO drive of +17 dBm , low side LO , in a downconversion application with $\mathrm{LO}=2100 \mathrm{MHz}, \mathrm{RF}=2200 \mathrm{MHz}, \mathrm{IF}=100 \mathrm{MHz}$.

| Absolute Maximum Rating |
| :--- | :--- |
| Abarameter Rating <br> Operating Case Temperature -40 to $+85^{\circ} \mathrm{C}$ <br> Storage Temperature -65 to $+100^{\circ} \mathrm{C}$ <br> RF Input Power +23 dBm |

Operation of this device above any of these parameters may cause permanent damage.

## Ordering Information

| Part No. | Description |
| :--- | :--- |
| WJZ1020H | Broadband Surface Mount Mixer |
| WJZ1020H-PCB | Fully-Assembled Mixer Application Board |

Standard T/R reel size $=500$ pieces on a 13 " reel.
Specifications and information are subject to change without notice

WJZ1020H
TriQuint
SEMICONDUCTOR

## Performance Charts



Isolation vs LO Frequency


WJZ1020H

## Mechanical Information

This package is lead-free/RoHS-compliant. The plating material is ENIG " Electroless Nickel Immersion Gold" It is compatible with leaded and lead-free (maximum $260^{\circ} \mathrm{C}$ reflow temperatures) Also recommend adding active flux of $2 \%$ during solder reflow.


## Outline Drawing

Land Pattern / Mounting Configuration


PAD MOUNTING GEOMETRY

## Notes:

1. Package unit weight is 2.0 grams max.
2. Dimensions are expressed in inches. Dimensions in brackets are millimeter equivalents.
3. Tolerance . $\mathrm{XXX}+/-.015, . \mathrm{XX}+/-.02$
4. Package circuit board material: .021" FR-4, 2 layers, .025" total thickness.
5. Land pattern ground vias are critical for RF grounding considerations. A minimum of 12 ground vias (min. diameter of 20 mil or $51 \mu \mathrm{~m}$ ) underneath the device is required.
6. PC board trace width depends on the board material and thickness.
7. Blocking capacitors are required on the ports (pins $2,4,6$ ) if any dc signal is present.

## Product Marking

The component will be marked with a "WJZ1020H" designator followed by an alphanumeric lot code on the top surface of the package.

Tape and reel specifications for this part will be located on the website in the "Application Notes" section.

Functional Pin Layout


Top view

| Pin No. | Function |
| :---: | :---: |
| 2 | RF |
| 4 | IF |
| 6 | LO |
| $1,3,5$ |  |
| Backside Metal | GND |

